

T|PACK secures new capital for future growth

Third Round of Funding Provides \$3.5 Million Enabling Company to Grow and Expand Technology Offerings to Telecommunications Equipment Manufacturers in North America and Asia

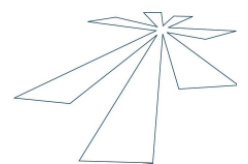
COPENHAGEN, Denmark – March 16, 2010 – TPACK (www.TPACK.com), an industry-leading provider of cutting-edge silicon ICs that provide core data transport and switching functions to leading telecom and networking equipment suppliers, today announced it has received \$3.5 million USD to close its third round of funding and confirming the investors' continued confidence in TPACK's technology, business model and strong customer uptake.

The new injection of capital will strengthen TPACK's focus on growth and expansion of the successful P-OCKET OTN Mapper platform and 100 Gbps Carrier Switches and Traffic Managers. The company anticipates that this will be the last round of funding required as the company expects to be profitable this year.

"We believe that TPACK has a strong, field-proven technology platform and a compelling business model," said Ulrik Jørring, Senior Vice President, Vækstfonden. "We were particularly impressed by TPACK's existing customer portfolio and their positive feedback on TPACK as a valuable partner and supplier. On this basis, we are confident that this round of funding will strongly position TPACK for further growth and will enable them to take full advantage of the fast development of the OTN market."

TPACK's SOFTSILICON model offers a compelling business case for telecommunications equipment manufacturers by providing short time-to-market, low risk and faster return on investment than silicon ASSPs.

"The market has responded positively to TPACK's new business model and we are seeing increased interest particularly in our OTN Mapper and cross connects solutions," explained Colin Macnab, CEO of TPACK. "With this new funding, we now have the means to expand our activities in North America and Asia and aggressively pursue important new developments, such as ODU0, ODUflex, and 100G mappers and carrier grade switches which are needed for the next generation of networks."



About TPACK

TPACK delivers cutting edge Silicon ICs providing core data transport and switching functions to leading Telecom and Networking equipment suppliers. TPACK's SOFTSILICON products support the fastest deployment of new Carrier Class Packet and Optical Network standards, providing the most flexible, cost and power effective implementations throughout the life of the equipment. TPACK's customer base includes Tier 1 equipment providers who account for more than 50% of the optical transport equipment market.

TPACK is a privately held company headquartered in Copenhagen, Denmark, with offices in Palo Alto, California.

For more information, visit www.tpack.com.

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